



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

FEB 07 2002

Applicant: Abbott Art Unit: 2826 2800 MAIL ROOM  
Serial No.: 09/525,105 Examiner: Williams, A.  
Filed: 03/14/00 Docket: TI-28098

*[Handwritten signatures and initials]*

For: **GOLD SPOT PLATED LEADFRAMES FOR SEMICONDUCTOR DEVICES  
AND METHOD OF FABRICATION**

**AMENDMENT 37 CFR 1.115**

January 14, 2002

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. 1.8 (A)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail bearing sufficient postage in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231 on January 14, 2002.

Emily C. Champlin  
Date: 1/14/02

Responsive to the Office Action of September 20, 2001, please amend the application as follows:

Claim 1. (Amended) A leadframe for use with packaged integrated circuit chips comprising:  
a plated layer of gold selectively covering [outer areas]  
segments of said leadframe external to said package,  
intended for solder attachment.

Claims 2. (Amended) A leadframe for use with packaged integrated circuit chips,  
having a chip mount pad and a plurality of lead segments,  
comprising: